

Customer Process Change Notification Form PCN-2010-406

Part Information

Cirrus Logic Part # / Quantity

| | | | |
|-------------|-------------|-------------|-------------|
| CS4334-KSZ | CS4335-KSZ | CS4338-KSZ | CS4339-KSZ |
| CS4334-KSZR | CS4335-KSZR | CS4338-KSZR | CS4339-KSZR |

PCN Effective Date:

Lot Effective Date:

Cirrus P/N Change: Yes No

(Contact the sales representative for availability of samples if applicable)

If yes, provide new part number:

Additional Part Number (use if more space is needed)

[Click here to attach a file](#)

Package Mark Change: Yes No

If Yes, briefly explain:

[Any Fab, Assembly, or Design changes results in pack mark changes, please provide detail]

Reason for Change:

- | | |
|--|--|
| <input type="checkbox"/> Design/New Rev | <input type="checkbox"/> Fab Process |
| <input type="checkbox"/> Assembly Site | <input type="checkbox"/> Additional Assembly Source |
| <input type="checkbox"/> Fab Site | <input checked="" type="checkbox"/> Assembly Process |
| <input type="checkbox"/> Other (Specify) | <input type="checkbox"/> Additional Fab Source |

Description of Change:

- | | |
|---|--|
| <input type="checkbox"/> Fix Errata | <input type="checkbox"/> Yield Enhancement |
| <input type="checkbox"/> Fix Known Bug | <input type="checkbox"/> Performance Improvement |
| <input checked="" type="checkbox"/> Other (specify) | |


Reduce flag paddle size and standardize bond wire diameter for the above listed devices assembled in 8 LD SOIC.

Summary of Bill of Material Change:

8 LD SOIC CURRENT BOM NEW STANDARD BOM

Additional Information


 Click here to attach a file

 Click here to attach a file

Quality and Reliability Impact:

Qualification Data Required? Yes No


Additional Information

 Reliability Report
QRR100807.pdf
27.83 KB

Data Sheet Change Required? Yes No

If Yes, briefly explain:


Additional Information

 Click here to attach a file

Software Change Required? Yes No

If Yes, briefly explain:

Additional Information

 Click here to attach a file

Customer Acknowledgement and Agreement

Acknowledged and Agreed as of the Date written below:

Customer Company _____
Name:

Customer Contact _____
Name:

Title: _____

Signature: _____

Date:

Customer Agreed Customer Reject Not Applicable

Customer Comments:

Description of change:

Reduce flag paddle size and standardize bond wire diameter for the above listed devices assembled in 8 LD SOIC.

Summary of Bill of Material Change:

| 8 LD SOIC | CURRENT BOM | NEW STANDARD BOM |
|----------------------|------------------------|-------------------------|
| Mold Compound | Sumitomo G600 | no change |
| Die Attach | Ablebond 8290 | no change |
| Wire | 1.0 mil Au | 0.8 mil Au |
| Leadframe | 0.095" x 0.130" | 0.090" x 0.090" |
| Finish | Matte Sn, 100% | no change |



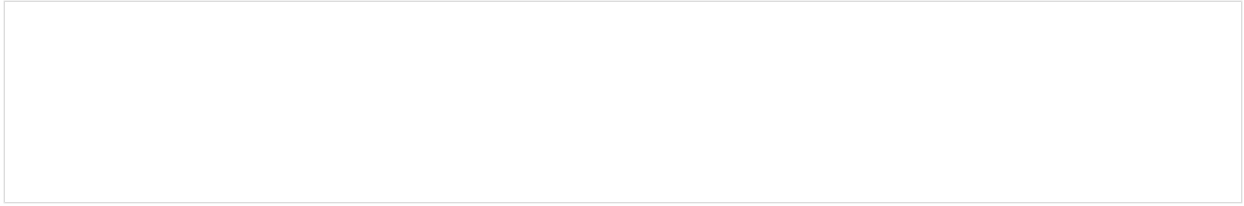
Qualification Reliability Report


Report: QRR100807
Date: 9/1/2010
Approved by: Mike Klucher

| Purpose | Results |
|---|---------------------------|
| Qualification of 8 SOIC package family with 0.8mil Au wire assembled at ANST. | Qualification successful. |

| Background Information | | | | | |
|------------------------|--------------|------------------------|--------|---------------------|---------|
| Assembly: | ANST (China) | Package Family: | 8 SOIC | Lead Finish: | Pb-free |
| Qual Vehicle: | CS1500 | | | | |

| Stress Name | Method | Conditions | Lot | Read Point | Results (Fail/Sample) |
|--|-------------|---|-----|-----------------|--------------------------|
| Precondition MSL-2 | JESD22-A113 | 24HR 125 °C Bake 168HR 85°C/60%RH Soak 3 pass 260 °C reflow | 1 | Precondition | 0 / 231 |
| | | | 2 | Precondition | 0 / 154 |
| | | | 3 | Precondition | 0 / 77 |
| | | | 4 | Precondition | 0 / 231 |
| HAST (Highly Accelerated Stress Test) | JESD22-A110 | 130 °C 85 %RH With Bias | 1 | 96 Hours | 0 / 77 |
| | | | 2 | 96 Hours | 0 / 77 |
| | | | 3 | 96 Hours | 0 / 77 |
| Temperature Cycle | JESD22-A104 | Condition C -65°C +150°C air to air | 1 | 500 Cycles | 0 / 77 |
| | | | 2 | 500 Cycles | 0 / 77 |
| | | | 3 | 500 Cycles | 0 / 77 |
| Tomography (CSAM) | J-STD-035 | | 1 | Post Temp Cycle | 0 / 11 |
| | | | 2 | Post Temp Cycle | 0 / 11 |
| | | | 3 | Post Temp Cycle | 0 / 11 |
| Autoclave/PPOT | JESD22-A102 | 121 °C 100% R.H. | 1 | 96 Hours | 0 / 77 |
| | | | 2 | 96 Hours | 0 / 77 |
| | | | 3 | 96 Hours | 0 / 77 |
| Solderability | JESD22-B102 | 93 °C steam aging 8 Hours 245 °C solder bath 5 Seconds | 1 | Solderability | 0 / 15 |
| HTSL (High Temperature Storage Life) | JESD22-A103 | 150 °C | 1 | 1000 Hours | 0 / 77 |
| | | | 2 | 1000 Hours | 0 / 77 |
| | | | 3 | 1000 Hours | 0 / 77 |



| | | | |
|---|--|-------------------------|-----------|
|  | Title: CUSTOMER PROCESS CHANGE NOTIFICATION FORM | | |
| | Digitally Signed By: | Doc No: 4-QUAL-00017 | Rev: D |

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